

Merit

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*This certificate is granted and awarded by the authority of the MedAccred Management Council to:*

## ***Benchmark Electronics, Inc.***

*4065 Theurer Blvd  
Winona, MN 55987  
United States*

*This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in [www.eAuditNet.com](http://www.eAuditNet.com) on the Qualified Manufacturer's List (QML), to the revision in effect at the time of the audit for:*

## ***Printed Board Assemblies***

Certificate Number: 156012007502  
Expiration Date: 28 February 2027  
Accreditation Length: 18 Months

A handwritten signature in black ink, appearing to read "Jay Solomond".

**Jay Solomond**  
Executive Vice President & Chief Operating Officer

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## SCOPE OF ACCREDITATION

### Printed Board Assemblies

**Benchmark Electronics, Inc.**  
4065 Theurer Blvd  
Winona, MN 55987

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

### **AC8120 Rev B - MedAccred Audit Criteria for Printed Circuit Board Assemblies (to be used on audits on/AFTER 05-Mar-2023)**

04.0 General

05.0 Process Validation

06.0 Medical Record Keeping

6.1 Device Master Record (DMR)

6.2 Device History Record (DHR)

6.3 Product Traceability

07.0 Foreign Object Damage and Foreign Object Debris (FOD) Prevention

08.0 Electrostatic Discharge (ESD) Management

09.0 Calibration

10.0 Preventive Maintenance

12.0 Purchasing and Authentic Component Assurance

13.0 Process Control

14.0 CAD/CAM Data

15.0 Receipt, Inspection & Control of Incoming Material

16.0 Storage and Handling of Received Materials

17.0 Component Programming

17.2 PCBA–Level Component Programming

18.0 Electronic Component Preparation

19.0 Stencil Printing

20.0 Component Placement

20.1 Manual

20.3 Automated Part Placement

20.4 Build Through / Build Short

20.5 Through Hole Component Lead Trimming

21.0 In–Process Placement Verification / Inspection

21.1 General

21.2 Visual

- 21.3 Automated Optical Inspection (AOI)
- 21.4 X-Ray
- 22.0 Assembly Soldering Processes
  - 22.1 Reflow Soldering
  - 22.2 Wave Soldering
  - 22.3 Selective Soldering
  - 22.4 Hand Soldering
- 23.0 Secondary Assembly
  - 23.1 Mechanical Part Installation
  - 23.5 Compliant Pin (Press Fit) Connector Installation
- 24.0 PCBA Cleaning Process and Control
- 26.0 Adhesive Bonding
- 27.0 Assembly Testing
  - 27.4 In-Circuit Testing
  - 27.5 Flying Probe Testing
  - 27.8 Functional Testing
- 28.0 Final Acceptance Inspection
- 29.0 Rework
- 30.0 Storage, Handling & Packaging of Finished Goods